



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2823  
Examiner: Suk San Foong

In Re PATENT APPLICATION Of:

Applicant(s) : Yasuo TANAKA

Serial No. : 09/660,484

Filed : September 12, 2000

METHOD OF MANUFACTURING  
SEMICONDUCTOR DEVICE

Attorney Ref. : OKI 262

AMENDMENT

August 23, 2002

Commissioner for Patents  
Washington, D.C. 20231  
**Box - Non-Final Action**

Sir:

This Amendment is filed in response to the Official Action dated May 23, 2002, the time for response to which is up to and including August 23, 2002. Please amend the above-referenced application as follows.

IN THE CLAIMS

Please cancel claims 1, 4-6 and 13, and amend claims 3, 7-9, 10-12 and 14-15 to read as follows:

3. (Twice Amended) The method as claimed in claim 7, further comprising:  
forming external terminals each having conductivity so as to be connected to  
said bumps respectively.

7. (Twice Amended) A method of manufacturing semiconductor devices,  
comprising:  
forming a plurality of semiconductor devices on a main surface of a  
semiconductor wafer, the plurality of semiconductor devices having a plurality of

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